

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	70	@ad<= "19991215" and (438/411). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:24
L2	187	@ad<= "19991215" and (438/461). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:24
L3	175	@ad<= "19991215" and (438/611). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:24
L4	408	@ad<= "19991215" and (438/613). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:24
L5	104	'chip' with 'size' with packag\$3 and 'hitherto'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:41
L7	10	((("6060373") or ("6083811") or ("6159837") or ("6297560") or ("6590257")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/31 09:34
L8	2	"20020030258"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:34
L9	37	@ad<="19991215" and 'chip' with 'size' with packag\$3 and 'hitherto'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:55
L10	1	"6159837".PN.	USPAT; USOCR	OR	ON	2006/01/31 09:42
L11	1	"6060373".PN.	USPAT; USOCR	OR	ON	2006/01/31 09:42
L12	15	@ad<="19991215" and 'chip' with 'size' with packag\$3 same 'wafer' with 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:04

L14	1497	@ad<= "19991215" and (438/106). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:57
L15	486	@ad<= "19991215" and (438/107). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:57
L16	335	@ad<= "19991215" and (438/108). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:57
L17	1	"5943591".PN.	USPAT; USOCR	OR	ON	2006/01/31 10:02
L20	5	@ad<="19991215" and 'chip size package' and 'silicon wafer' with 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:17
L21	2	@ad<="19991215" and 'flip chip' and 'silicon wafer' with 'thickness' and 'sealing resin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:18
L22	378	@ad<="19991215" and 'flip chip' and 'sealing resin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:18
L23	241	@ad<="19991215" and 'flip chip' and 'sealing resin' and 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:18
L24	154	@ad<="19991215" and 'flip chip' and 'sealing resin' same 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:20
L25	47	@ad<="19991215" and 'chip size package' and 'sealing resin' same 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:21
S1	403	@ad<= "19991215" and (438/113-114).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:56
S2	1895	@ad<= "19991215" and (438/459-464).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:11

S4	432	@ad<= "19991215" and (438/631). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:12
S5	197	@ad<= "19991215" and (438/690). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:12
S6	138	@ad<= "19991215" and (438/33). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:12
S7	4	(("6297560") or ("6083811")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/30 16:16
S8	2	"20040099937"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:16
S9	104	@ad<= "19991215" and (438/759). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:16